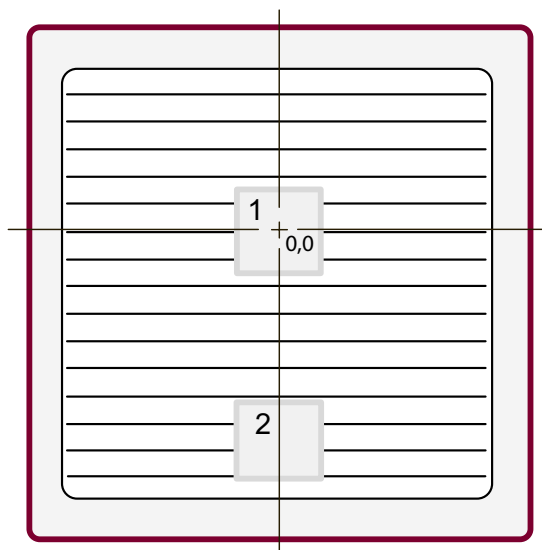


Pad Layout



Backside: Drain

Die Specifications

| Device | Die Dimensions | | | Back Side Metal | Back Side | Bonding Pad Material |
|--------|----------------------------|---------------------------|------------------|-----------------|-----------|----------------------|
| | Length ¹ (mils) | Width ¹ (mils) | Thickness (mils) | | | |
| TN2524 | 45 | 45 | 11 ± 1.5 | Au | Drain | Al/Cu/Si |

Bonding Pad Description

| Pad # | Function | x Position ² (mils) | y Position ² (mils) | x Size (mils) | y Size (mils) |
|-------|----------|--------------------------------|--------------------------------|---------------|---------------|
| 1 | Source | 0 | 0 | 6.5 | 6.5 |
| 2 | Gate | 0 | -17.8 | 6.4 | 5.5 |

Notes:

1. Maximum values.
2. Position referenced to center of pad.

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